

N-Channel 100-V (D-S) MOSFET

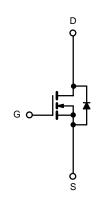
PRODUCT SUMMARY				
V _{(BR)DSS} (V)	r _{DS(on)} (Ω)	I _D (A)		
100	0.030 at V _{GS} = 10 V	45		
	0.035 at V _{GS} = 4.5 V	40		

FEATURES

- TrenchFET[®] Power MOSFETS
- 175 °C Junction Temperature
- Low Thermal Resistance Package







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _C = 25 °C, unless oth	erwise noted		
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	100	v
Gate-Source Voltage		V _{GS}	± 20	v
Continuous Drain Current ($T_1 = 175 \text{ °C}$)	T _C = 25 °C	1-	45	
Continuous Drain Current $(1j = 175 C)$	T _C = 125 °C	I _D	30	
Pulsed Drain Current	I _{DM}	135	- A	
Avalanche Current	I _{AR}	35		
Repetitive Avalanche Energy ^a	L = 0.1 mH	E _{AR}	61	mJ
	T _C = 25 °C	Р	127 ^b	14/
Maximum Power Dissipation ^a	T _A = 25 °C ^c	– P _D –	3.75	W
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	(PCB Mount) ^c	R _{thJA}	40	°C/W	
Junction-to-Case (Drain)		R _{thJC}	1.4	0/11	

Notes:

a. Duty cycle \leq 1 %.

b. See SOA curve for voltage derating.

c. When Mounted on 1" square PCB (FR-4 material).

* Pb containing terminations are not RoHS compliant, exemptions may apply.

SPECIFICATIONS $T_J = 25 \text{ °C}$, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{SS} = 0 V, I_D = 250 \mu A$	100			v	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$			3	v	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current		$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}$			1		
	I _{DSS}	$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$			50		
		$V_{DS} = 80 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 \text{ °C}$			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	75			А	
		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 5 \text{ A}$		0.030		Ω	
		$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 3 \text{ A}$		0.035			
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = 10 V, I _D = 5 A, T _J = 125 °C		0.050			
		V _{GS} = 10 V, I _D = 3 A, T _J = 175 °C		0.062		1	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 15 A	10			S	
Dynamic ^b	•		4	• •			
Input Capacitance	C _{iss}			3100		pF	
Output Capacitance	C _{oss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz		410			
Reverse Transfer Capacitance	C _{rss}			150			
Total Gate Charge ^c	Qg			35	60	nC	
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 50$ V, $V_{GS} = 10$ V, $I_{D} = 40$ A		11			
Gate-Drain Charge ^c	Q _{gd}			9			
Gate Resistance	R _G			1.7		Ω	
Turn-On Delay Time ^c	t _{d(on)}			11	20	ns	
Rise Time ^c	t _r	V_{DD} = 50 V, R_L = 1.25 Ω		12	20		
Turn-Off Delay Time ^c	t _{d(off)}	$\text{I}_\text{D} \cong$ 40 A, V_GEN = 10 V, R_G = 2.5 Ω		30	45		
Fall Time ^c	t _f			12	20		
Source-Drain Diode Ratings and Cha	aracteristics T	_C = 25 °C ^b					
Continuous Current	ا _S				40	٨	
Pulsed Current	I _{SM}				120	A	
Forward Voltage ^a	V _{SD}	$I_{F} = 30 \text{ A}, \text{ V}_{GS} = 0 \text{ V}$		1.0	1.5	V	
Reverse Recovery Time	t _{rr}			60	100	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 30 A, di/dt = 100 A/µs		5	8	А	
Reverse Recovery Charge	Q _{rr}			0.15	0.4	μC	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %

b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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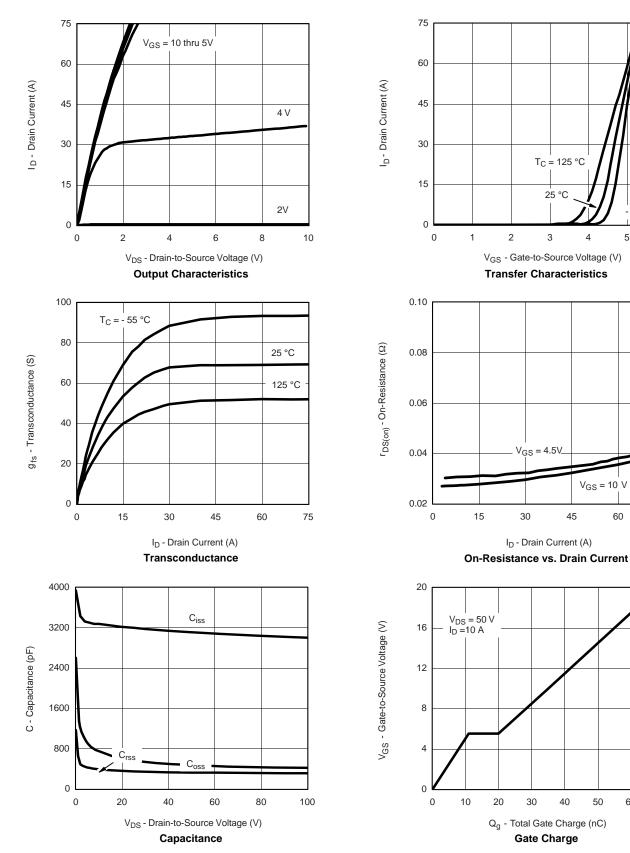


55 °C

T_C = 125 °C

25 °C

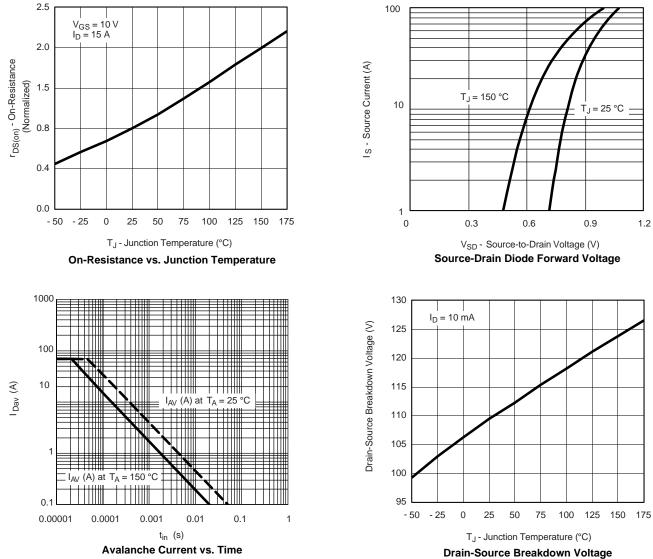
 $V_{GS} = 10 V$



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



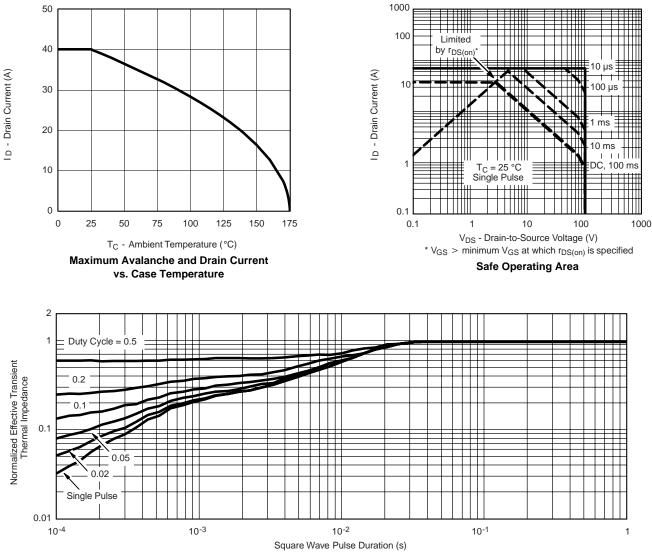




vs. Junction Temperature



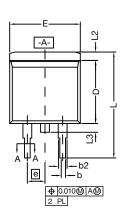
THERMAL RATINGS

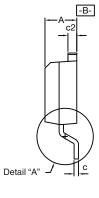


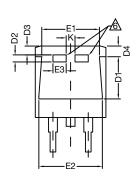
Normalized Thermal Transient Impedance, Junction-to-Case



TO-263 (D²PAK): 3-LEAD

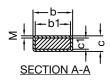








DETAIL A (ROTATED 90°)

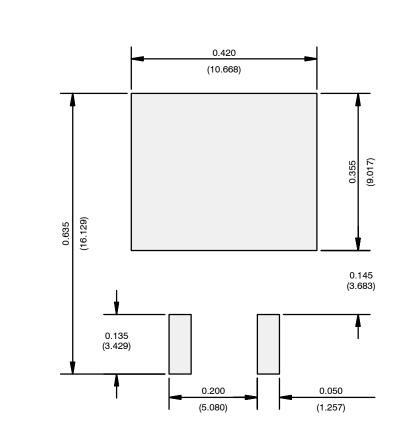


		INCHES		MILLIMETERS			
DIM.		MIN.	MAX.	MIN.	MAX.		
A		0.160	0.190	4.064	4.826		
b		0.020	0.039	0.508	0.990		
	b1	0.020	0.035	0.508	0.889		
	b2	0.045	0.055	1.143	1.397		
с*	Thin lead	0.013	0.018	0.330	0.457		
C	Thick lead	0.023	0.028	0.584	0.711		
c1	Thin lead	0.013	0.017	0.330	0.431		
	Thick lead	0.023	0.027	0.584	0.685		
	c2	0.045	0.055	1.143	1.397		
	D	0.340	0.380	8.636	9.652		
D1		0.220	0.240	5.588	6.096		
D2		0.038	0.042	0.965	1.067		
D3		0.045	0.055	1.143	1.397		
D4		0.044	0.052	1.118	1.321		
E		0.380	0.410	9.652	10.414		
	E1	0.245	-	6.223	-		
E2		0.355	0.375	9.017	9.525		
E3		0.072	0.078	1.829	1.981		
	е	0.100 BSC 2.54		BSC			
	К	0.045	0.055	1.143	1.397		
L		0.575	0.625	14.605	15.875		
L1		0.090	0.110	2.286	2.794		
L2		0.040	0.055	1.016	1.397		
L3		0.050	0.070	1.270	1.778		
	L4	0.010 BSC		0.254 BSC			
М		-	0.002	-	0.050		
ECN: T13-0707-Rev. K, 30-Sep-13 DWG: 5843							

Notes

- 1. Plane B includes maximum features of heat sink tab and plastic.
- 2. No more than 25 % of L1 can fall above seating plane by max. 8 mils.
- 3. Pin-to-pin coplanarity max. 4 mils.
- 4. *: Thin lead is for SUB, SYB.
 - Thick lead is for SUM, SYM, SQM.
- 5. Use inches as the primary measurement.





RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead

Recommended Minimum Pads Dimensions in Inches/(mm)



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